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PATENT

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Date July 25 2002 Stephanie Jansen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Tongbi Jiang
Serial No. : 09/365,356
Filed : July 30, 1999
Title : METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD SEMICONDUCTOR PACKAGED DEVICES

Attorney Docket No.: 500182.01 (660073.774)
Group Art Unit : 2813
Examiner : Nema O. Berezny

Box Non-Fee Amendment
Commissioner of Patents
Washington, DC 20231

AMENDMENT

Sir:

Applicant acknowledges receipt of the Office Action dated April 29, 2002.

In the Claims:

Please cancel claims 5, 6, 7, 17 and 39, amend claims 1, 11, 38, 42, and add new claims 50-53 as follows:

- SUB HI**
F1
1. (Three Times Amended) A semiconductor device package, comprising:
a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of opposed lateral edges;
at least one electrically conductive external terminal;

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